

RESIN COMPOSITION, PREPREG, AND LAMINATED SHEET

ABSTRACT

There is provided a resin composition that, despite the fact that the content of an inorganic filler is on approximately the same level as that of the conventional resins, can provide a cured resin product that has a low coefficient of thermal expansion in a plane direction and possesses excellent heat resistance and flame retardance. The resin composition comprises an epoxy resin (A), a maleimide compound (B), a curing agent (C), and an inorganic filler (D), the epoxy resin (A) being represented by formula (I):

